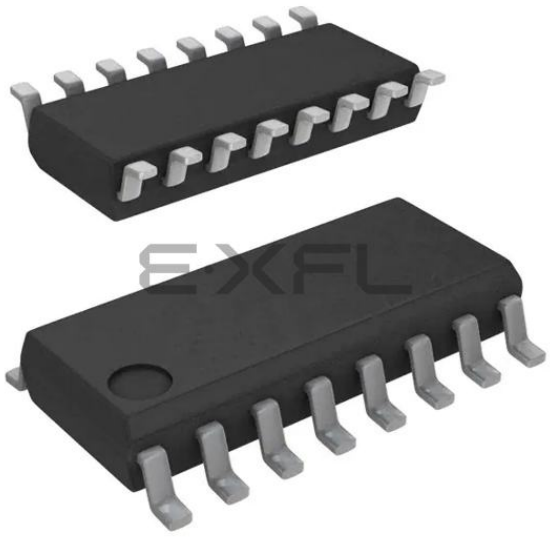

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Not For New Designs
Core Processor	8051
Core Size	8-Bit
Speed	25MHz
Connectivity	SMBus (2-Wire/I²C), SPI, UART/USART
Peripherals	Cap Sense, POR, PWM, WDT
Number of I/O	13
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	16-SOIC (0.154", 3.90mm Width)
Supplier Device Package	16-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051f828-gsr

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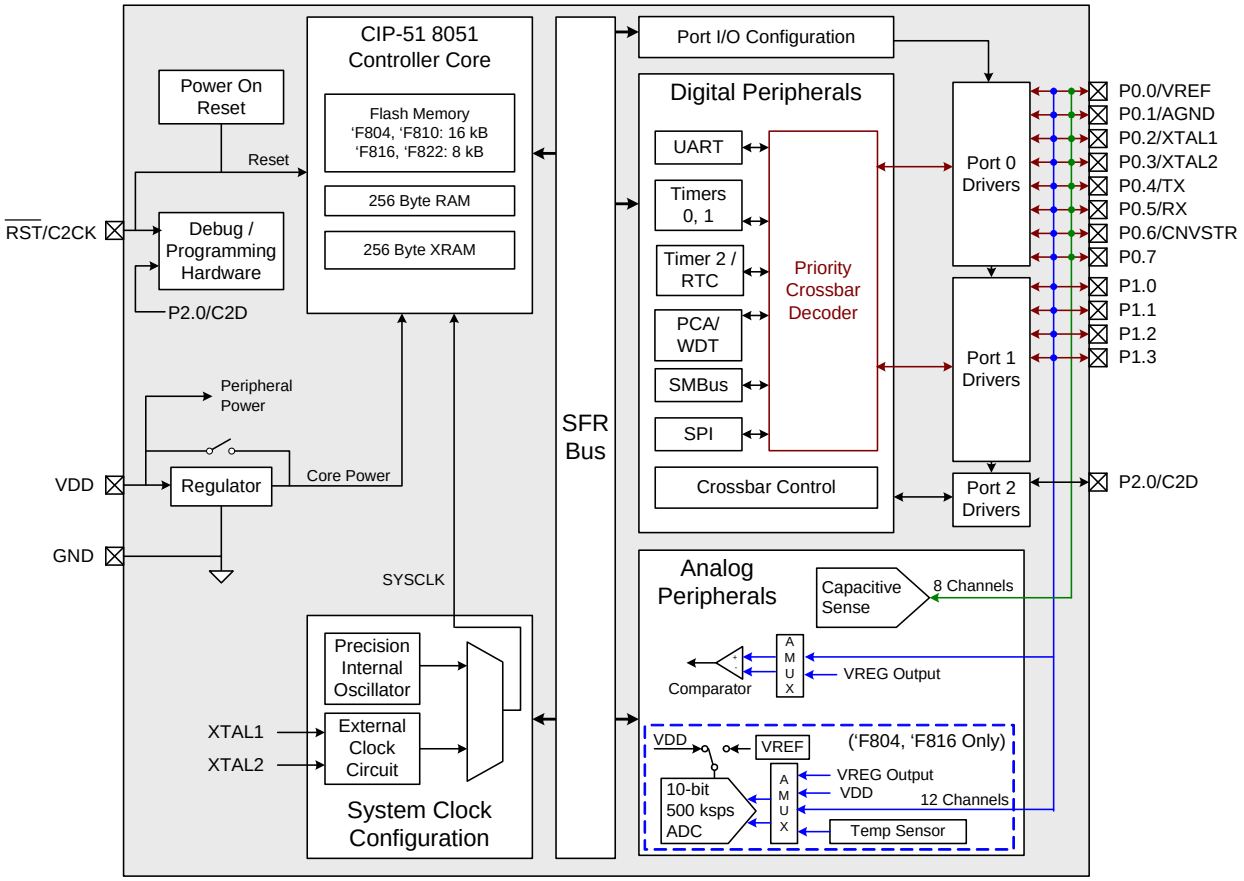

Figure 1.5. C8051F804, C8051F810, C8051F816, C8051F822 Block Diagram

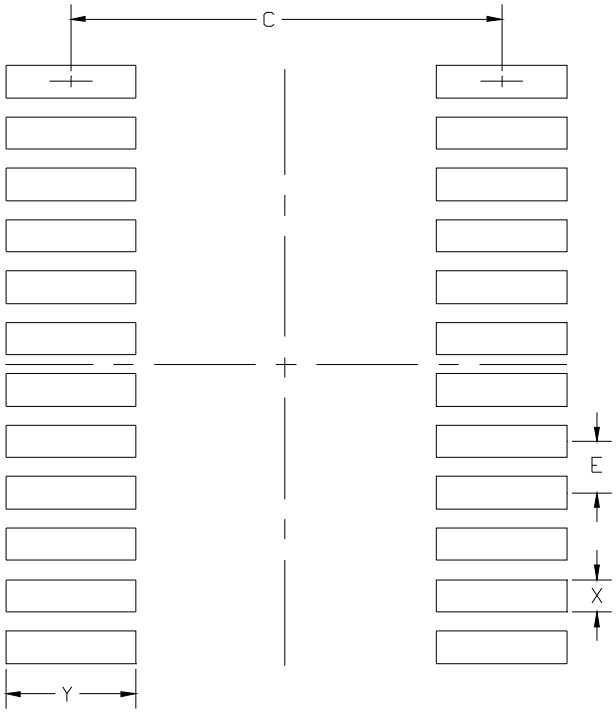

Figure 5.2. QSOP-24 PCB Land Pattern

Table 5.2. QSOP-24 PCB Land Pattern Dimensions

Dimension	Min	Max
C	5.20	5.30
E	0.635 BSC	
X	0.30	0.40
Y	1.50	1.60

Notes:

General

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. This land pattern design is based on the IPC-7351 guidelines.

Solder Mask Design

3. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 µm minimum, all the way around the pad.

Stencil Design

4. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
5. The stencil thickness should be 0.125 mm (5 mils).
6. The ratio of stencil aperture to land pad size should be 1:1 for all perimeter pads.

Card Assembly

7. A No-Clean, Type-3 solder paste is recommended.
8. The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

Table 7.9. ADC0 Electrical Characteristics

V_{DD} = 3.0 V, VREF = 2.40 V (REFSL=0), –40 to +85 °C unless otherwise specified.

Parameter	Conditions	Min	Typ	Max	Units
DC Accuracy					
Resolution			10		bits
Integral Nonlinearity		—	±0.5	±1	LSB
Differential Nonlinearity	Guaranteed Monotonic	—	±0.5	±1	LSB
Offset Error		–2	0	2	LSB
Full Scale Error		–2	0	2	LSB
Offset Temperature Coefficient		—	45	—	ppm/°C
Dynamic performance (10 kHz sine-wave single-ended input, 1 dB below Full Scale, 200 ksps)					
Signal-to-Noise Plus Distortion		54	60	—	dB
Total Harmonic Distortion	Up to the 5th harmonic	—	75	—	dB
Spurious-Free Dynamic Range		—	–90	—	dB
Conversion Rate					
SAR Conversion Clock		—	—	8.33	MHz
Conversion Time in SAR Clocks	10-bit Mode 8-bit Mode	13 11	— —	— —	clocks clocks
Track/Hold Acquisition Time	V_{DD} >= 2.0 V V_{DD} < 2.0 V	300 2.0	— —	— —	ns µs
Throughput Rate		—	—	500	ksps
Analog Inputs					
ADC Input Voltage Range		0	—	VREF	V
Sampling Capacitance	1x Gain 0.5x Gain	— —	5 3	— —	pF pF
Input Multiplexer Impedance		—	5	—	kΩ
Power Specifications					
Power Supply Current	Operating Mode, 500 ksps	—	630	1000	µA
Power Supply Rejection		—	–70	—	dB

Table 7.13. Comparator Electrical Characteristics

V_{DD} = 3.0 V, –40 to +85 °C unless otherwise noted.

Parameter	Conditions	Min	Typ	Max	Units
Response Time: Mode 0, Vcm* = 1.5 V	CP0+ – CP0– = 100 mV	—	220	—	ns
	CP0+ – CP0– = –100 mV	—	225	—	ns
Response Time: Mode 1, Vcm* = 1.5 V	CP0+ – CP0– = 100 mV	—	340	—	ns
	CP0+ – CP0– = –100 mV	—	380	—	ns
Response Time: Mode 2, Vcm* = 1.5 V	CP0+ – CP0– = 100 mV	—	510	—	ns
	CP0+ – CP0– = –100 mV	—	945	—	ns
Response Time: Mode 3, Vcm* = 1.5 V	CP0+ – CP0– = 100 mV	—	1500	—	ns
	CP0+ – CP0– = –100 mV	—	5000	—	ns
Common-Mode Rejection Ratio		—	1	4	mV/V
Positive Hysteresis 1	Mode 2, CP0HYP1–0 = 00b	—	0	1	mV
Positive Hysteresis 2	Mode 2, CP0HYP1–0 = 01b	2	5	10	mV
Positive Hysteresis 3	Mode 2, CP0HYP1–0 = 10b	7	10	20	mV
Positive Hysteresis 4	Mode 2, CP0HYP1–0 = 11b	10	20	30	mV
Negative Hysteresis 1	Mode 2, CP0HYN1–0 = 00b	—	0	1	mV
Negative Hysteresis 2	Mode 2, CP0HYN1–0 = 01b	2	5	10	mV
Negative Hysteresis 3	Mode 2, CP0HYN1–0 = 10b	7	10	20	mV
Negative Hysteresis 4	Mode 2, CP0HYN1–0 = 11b	10	20	30	mV
Inverting or Non-Inverting Input Voltage Range		–0.25	—	V_{DD} + 0.25	V
Input Offset Voltage		–7.5	—	7.5	mV
Power Specifications					
Power Supply Rejection		—	0.1	—	mV/V
Powerup Time		—	10	—	µs
Supply Current at DC	Mode 0	—	20	—	µA
	Mode 1	—	8	—	µA
	Mode 2	—	3	—	µA
	Mode 3	—	0.5	—	µA

Note: Vcm is the common-mode voltage on CP0+ and CP0–.

8.3.2. Tracking Modes

The AD0TM bit in register ADC0CN enables "delayed conversions", and will delay the actual conversion start by three SAR clock cycles, during which time the ADC will continue to track the input. If AD0TM is left at logic 0, a conversion will begin immediately, without the extra tracking time. For internal start-of-conversion sources, the ADC will track anytime it is not performing a conversion. When the CNVSTR signal is used to initiate conversions, ADC0 will track either when AD0TM is logic 1, or when AD0TM is logic 0 and CNVSTR is held low. See Figure 8.2 for track and convert timing details. Delayed conversion mode is useful when AMUX settings are frequently changed, due to the settling time requirements described in Section “8.3.3. Settling Time Requirements” on page 49.

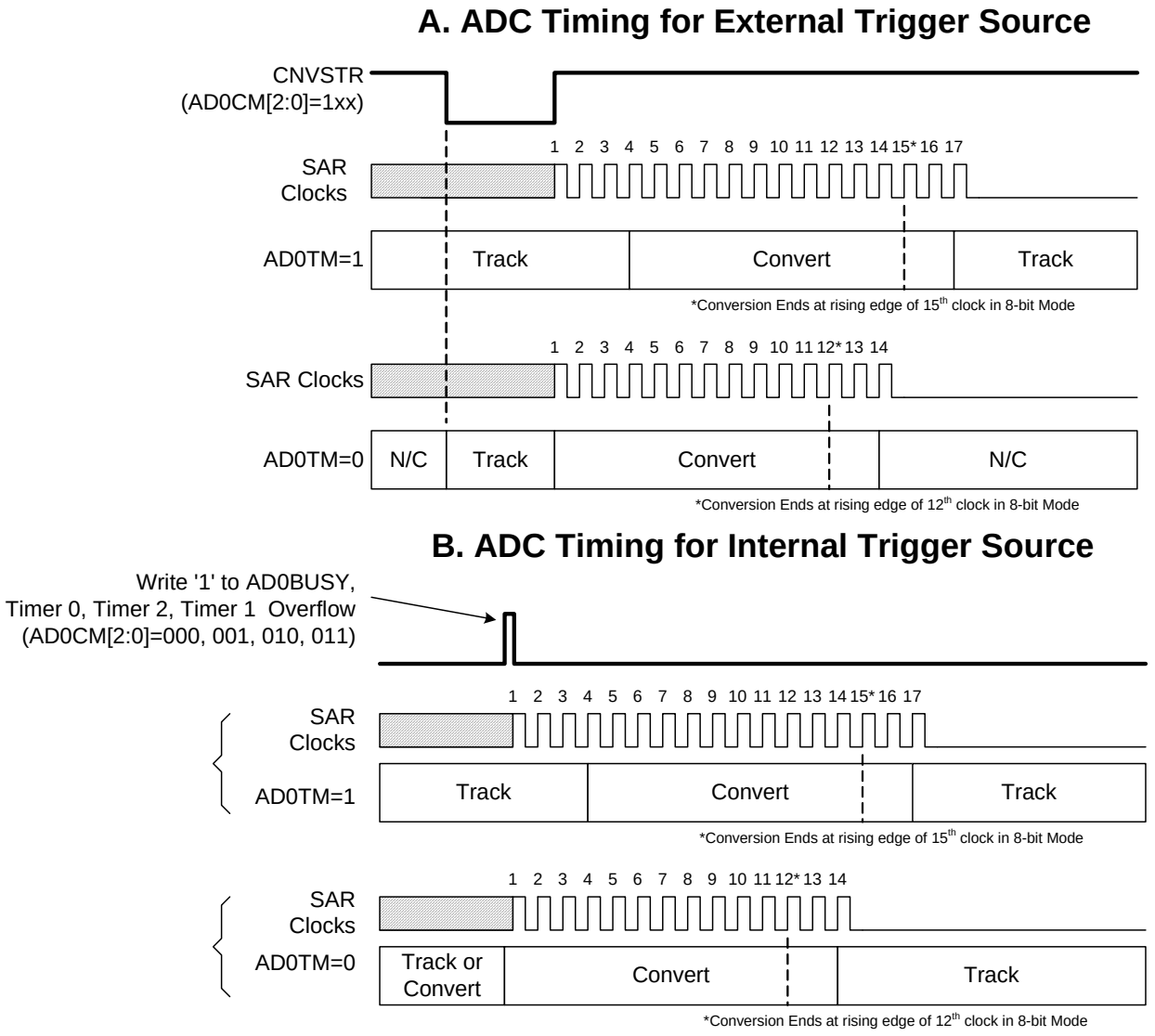

Figure 8.2. 10-Bit ADC Track and Conversion Example Timing

8.5. ADC0 Analog Multiplexer

ADC0 on the C8051F800/1/2/3/4/5, C8051F812/3/4/5/6/7, C8051F824/5/6, and C8051F830/1/2 uses an analog input multiplexer to select the positive input to the ADC. Any of the following may be selected as the positive input: Port 0 or Port 1 I/O pins, the on-chip temperature sensor, or the positive power supply (V_{DD}). The ADC0 input channel is selected in the ADC0MX register described in SFR Definition 8.9.

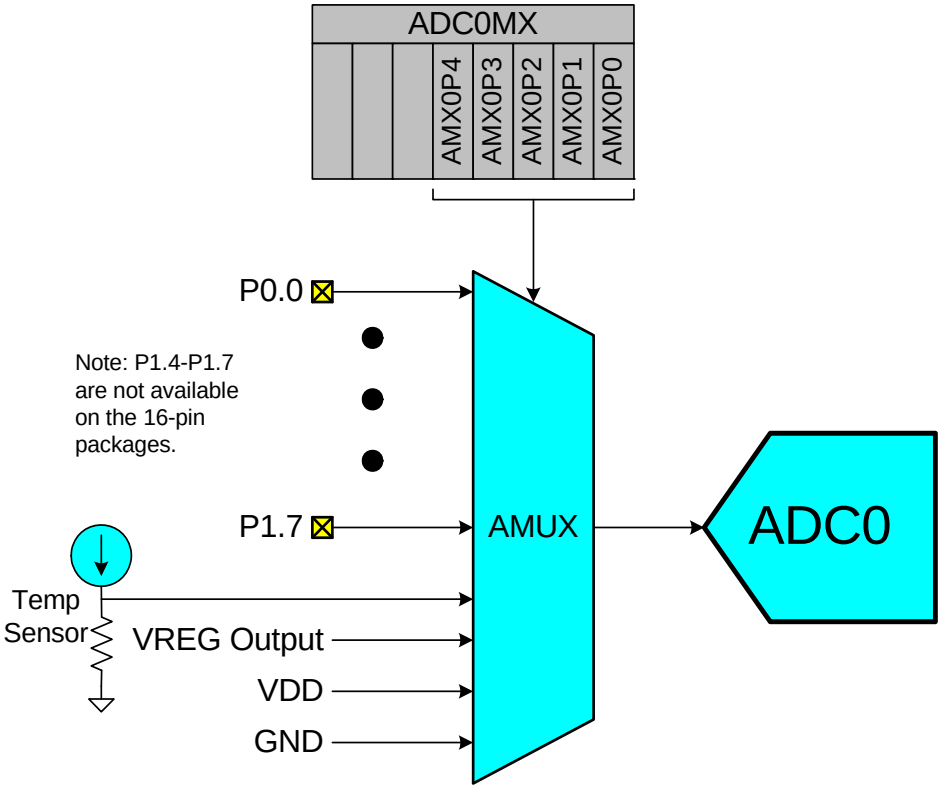

Figure 8.6. ADC0 Multiplexer Block Diagram

Important Note About ADC0 Input Configuration: Port pins selected as ADC0 inputs should be configured as analog inputs, and should be skipped by the Digital Crossbar. To configure a Port pin for analog input, set the corresponding bit in register PnMDIN to 0. To force the Crossbar to skip a Port pin, set the corresponding bit in register PnSKIP to 1. See Section “23. Port Input/Output” on page 138 for more Port I/O configuration details.

SFR Definition 8.9. ADC0MX: AMUX0 Channel Select

Bit	7	6	5	4	3	2	1	0
Name				AMX0P[3:0]				
Type	R	R	R	R/W				
Reset	0	0	0	1	1	1	1	1

SFR Address = 0xBB

Bit	Name	Function		
7:5	Unused	Read = 000b; Write = Don't Care.		
4:0	AMX0P[4:0]	**AMUX0 Positive Input Selection.**		
			20-Pin and 24-Pin Devices	**16-Pin Devices**
		00000:	P0.0	P0.0
		00001:	P0.1	P0.1
		00010:	P0.2	P0.2
		00011:	P0.3	P0.3
		00100:	P0.4	P0.4
		00101:	P0.5	P0.5
		00110:	P0.6	P0.6
		00111:	P0.7	P0.7
		01000	P1.0	P1.0
		01001	P1.1	P1.1
		01010	P1.2	P1.2
		01011	P1.3	P1.3
		01100	P1.4	Reserved.
		01101	P1.5	Reserved.
		01110	P1.6	Reserved.
		01111	P1.7	Reserved.
		10000:	Temp Sensor	Temp Sensor
		10001:	VREG Output	VREG Output
		10010:	VDD	VDD
		10011:	GND	GND
		10100 – 11111:	no input selected	

9. Temperature Sensor

An on-chip temperature sensor is included on the C8051F800/1/2/3/4/5, C8051F812/3/4/5/6/7, C8051F824/5/6, and C8051F830/1/2 which can be directly accessed via the ADC multiplexer in single-ended configuration. To use the ADC to measure the temperature sensor, the ADC mux channel should be configured to connect to the temperature sensor. The temperature sensor transfer function is shown in Figure 9.1. The output voltage (V_{TEMP}) is the positive ADC input when the ADC multiplexer is set correctly.

The TEMPE bit in register REF0CN enables/disables the temperature sensor, as described in SFR Definition 10.1. While disabled, the temperature sensor defaults to a high impedance state and any ADC measurements performed on the sensor will result in meaningless data. Refer to Table 7.11 for the slope and offset parameters of the temperature sensor.

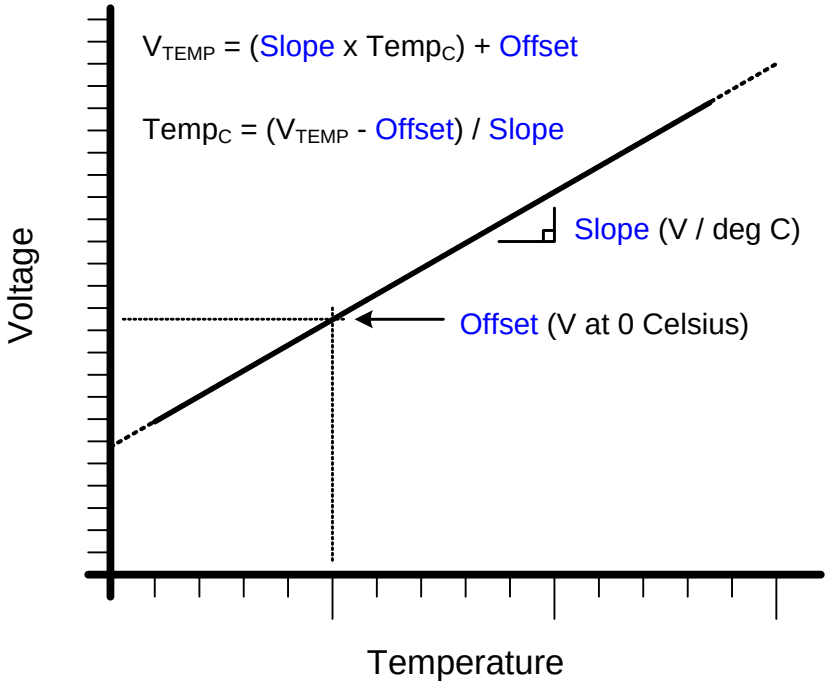

Figure 9.1. Temperature Sensor Transfer Function

9.1. Calibration

The uncalibrated temperature sensor output is extremely linear and suitable for relative temperature measurements (see Table 5.1 for linearity specifications). For absolute temperature measurements, offset and/or gain calibration is recommended. Typically a 1-point (offset) calibration includes the following steps:

1. Control/measure the ambient temperature (this temperature must be known).
2. Power the device, and delay for a few seconds to allow for self-heating.
3. Perform an ADC conversion with the temperature sensor selected as the ADC's input.
4. Calculate the offset characteristics, and store this value in non-volatile memory for use with subsequent temperature sensor measurements.

Figure 5.3 shows the typical temperature sensor error assuming a 1-point calibration at 0 °C.

Parameters that affect ADC measurement, in particular the voltage reference value, will also affect temperature measurement.

SFR Definition 11.1. REG0CN: Voltage Regulator Control

Bit	7	6	5	4	3	2	1	0
Name	STOPCF							
Type	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

SFR Address = 0xC9

Bit	Name	Function
7	STOPCF	**Stop Mode Configuration.** This bit configures the regulator's behavior when the device enters STOP mode. 0: Regulator is still active in STOP mode. Any enabled reset source will reset the device. 1: Regulator is shut down in STOP mode. Only the $\overline{\text{RST}}$ pin or power cycle can reset the device.
6:0	Reserved	Must write to 0000000b.

12.1. Comparator Multiplexer

C8051F80x-83x devices include an analog input multiplexer to connect Port I/O pins to the comparator inputs. The Comparator0 inputs are selected in the CPT0MX register (SFR Definition 12.3). The CMX0P3–CMX0P0 bits select the Comparator0 positive input; the CMX0N3–CMX0N0 bits select the Comparator0 negative input. **Important Note About Comparator Inputs:** The Port pins selected as comparator inputs should be configured as analog inputs in their associated Port configuration register, and configured to be skipped by the Crossbar (for details on Port configuration, see Section “23.6. Special Function Registers for Accessing and Configuring Port I/O” on page 152).

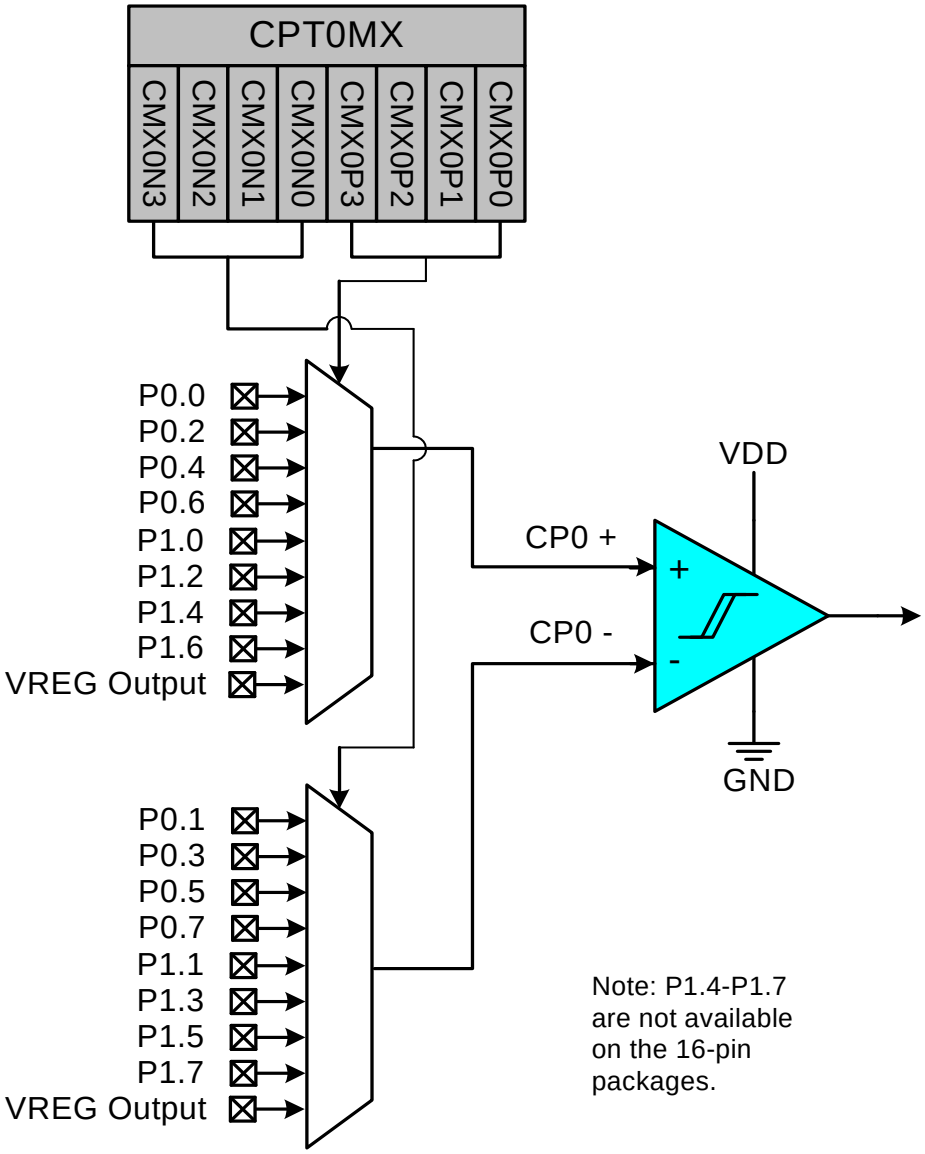

Figure 12.3. Comparator Input Multiplexer Block Diagram

SFR Definition 13.2. CS0CF: Capacitive Sense Configuration

Bit	7	6	5	4	3	2	1	0
Name		CS0CM[2:0]				CS0ACU[2:0]		
Type	R	R/W	R/W	R/W	R	R/W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

SFR Address = 0x9E

Bit	Name	Description
7	Unused	Read = 0b; Write = Don't care
6:4	CS0CM[2:0]	**CS0 Start of Conversion Mode Select.** 000: Conversion initiated on every write of 1 to CS0BUSY. 001: Conversion initiated on overflow of Timer 0. 010: Conversion initiated on overflow of Timer 2. 011: Conversion initiated on overflow of Timer 1. 100: Reserved. 101: Reserved. 110: Conversion initiated continuously after writing 1 to CS0BUSY. 111: Auto-scan enabled, conversions initiated continuously after writing 1 to CS0BUSY.
3	Unused	Read = 0b; Write = Don't care
2:0	CS0ACU[2:0]	**CS0 Accumulator Mode Select.** 000: Accumulate 1 sample. 001: Accumulate 4 samples. 010: Accumulate 8 samples. 011: Accumulate 16 samples 100: Accumulate 32 samples. 101: Accumulate 64 samples. 11x: Reserved.

Table 14.1. CIP-51 Instruction Set Summary

Mnemonic	Description	Bytes	Clock Cycles
Arithmetic Operations			
ADD A, Rn	Add register to A	1	1
ADD A, direct	Add direct byte to A	2	2
ADD A, @Ri	Add indirect RAM to A	1	2
ADD A, #data	Add immediate to A	2	2
ADDC A, Rn	Add register to A with carry	1	1
ADDC A, direct	Add direct byte to A with carry	2	2
ADDC A, @Ri	Add indirect RAM to A with carry	1	2
ADDC A, #data	Add immediate to A with carry	2	2
SUBB A, Rn	Subtract register from A with borrow	1	1
SUBB A, direct	Subtract direct byte from A with borrow	2	2
SUBB A, @Ri	Subtract indirect RAM from A with borrow	1	2
SUBB A, #data	Subtract immediate from A with borrow	2	2
INC A	Increment A	1	1
INC Rn	Increment register	1	1
INC direct	Increment direct byte	2	2
INC @Ri	Increment indirect RAM	1	2
DEC A	Decrement A	1	1
DEC Rn	Decrement register	1	1
DEC direct	Decrement direct byte	2	2
DEC @Ri	Decrement indirect RAM	1	2
INC DPTR	Increment Data Pointer	1	1
MUL AB	Multiply A and B	1	4
DIV AB	Divide A by B	1	8
DA A	Decimal adjust A	1	1
Logical Operations			
ANL A, Rn	AND Register to A	1	1
ANL A, direct	AND direct byte to A	2	2
ANL A, @Ri	AND indirect RAM to A	1	2
ANL A, #data	AND immediate to A	2	2
ANL direct, A	AND A to direct byte	2	2
ANL direct, #data	AND immediate to direct byte	3	3
ORL A, Rn	OR Register to A	1	1
ORL A, direct	OR direct byte to A	2	2
ORL A, @Ri	OR indirect RAM to A	1	2
ORL A, #data	OR immediate to A	2	2
ORL direct, A	OR A to direct byte	2	2
ORL direct, #data	OR immediate to direct byte	3	3
XRL A, Rn	Exclusive-OR Register to A	1	1
XRL A, direct	Exclusive-OR direct byte to A	2	2
XRL A, @Ri	Exclusive-OR indirect RAM to A	1	2
XRL A, #data	Exclusive-OR immediate to A	2	2
XRL direct, A	Exclusive-OR A to direct byte	2	2

Table 17.2. Special Function Registers (Continued)

SFRs are listed in alphabetical order. All undefined SFR locations are reserved

Register	Address	Description	Page
CS0CF	0x9E	CS0 Configuration	76
CS0MX	0x9C	CS0 Mux	81
CS0SE	0xBA	Auto Scan End Channel	78
CS0SS	0xB9	Auto Scan Start Channel	78
DERIVID	0xAD	Derivative Identification	96
DPH	0x83	Data Pointer High	88
DPL	0x82	Data Pointer Low	88
EIE1	0xE6	Extended Interrupt Enable 1	107
EIE2	0xE7	Extended Interrupt Enable 2	108
EIP1	0xF3	Extended Interrupt Priority 1	109
EIP2	0xF4	Extended Interrupt Priority 2	110
FLKEY	0xB7	Flash Lock And Key	119
HWID	0xB5	Hardware Identification	95
IE	0xA8	Interrupt Enable	105
IP	0xB8	Interrupt Priority	106
IT01CF	0xE4	INT0/INT1 Configuration	112
OSCICL	0xB3	Internal Oscillator Calibration	131
OSCICN	0xB2	Internal Oscillator Control	132
OSCXCN	0xB1	External Oscillator Control	134
P0	0x80	Port 0 Latch	153
P0MASK	0xFE	Port 0 Mask	151
P0MAT	0xFD	Port 0 Match	151
P0MDIN	0xF1	Port 0 Input Mode Configuration	154
P0MDOUT	0xA4	Port 0 Output Mode Configuration	154
P0SKIP	0xD4	Port 0 Skip	155
P1	0x90	Port 1 Latch	155
P1MASK	0xEE	P0 Mask	152

The following guidelines are recommended for any system that contains routines which write or erase Flash from code.

19.4.1. VDD Maintenance and the VDD Monitor

1. If the system power supply is subject to voltage or current "spikes," add sufficient transient protection devices to the power supply to ensure that the supply voltages listed in the Absolute Maximum Ratings table are not exceeded.
2. Make certain that the minimum VDD rise time specification of 1 ms is met. If the system cannot meet this rise time specification, then add an external VDD brownout circuit to the RST pin of the device that holds the device in reset until VDD reaches the minimum device operating voltage and re-asserts RST if VDD drops below the minimum device operating voltage.
3. Keep the on-chip VDD Monitor enabled and enable the VDD Monitor as a reset source as early in code as possible. This should be the first set of instructions executed after the Reset Vector. For C-based systems, this will involve modifying the startup code added by the C compiler. See your compiler documentation for more details. Make certain that there are no delays in software between enabling the VDD Monitor and enabling the VDD Monitor as a reset source. Code examples showing this can be found in “AN201: Writing to Flash from Firmware," available from the Silicon Laboratories website.

Note: On C8051F80x-83x devices, both the VDD Monitor and the VDD Monitor reset source must be enabled to write or erase Flash without generating a Flash Error Device Reset.

On C8051F80x-83x devices, both the VDD Monitor and the VDD Monitor reset source are enabled by hardware after a power-on reset.

4. As an added precaution, explicitly enable the VDD Monitor and enable the VDD Monitor as a reset source inside the functions that write and erase Flash memory. The VDD Monitor enable instructions should be placed just after the instruction to set PSWE to a 1, but before the Flash write or erase operation instruction.
5. Make certain that all writes to the RSTSRC (Reset Sources) register use direct assignment operators and explicitly DO NOT use the bit-wise operators (such as AND or OR). For example, "RSTSRC = 0x02" is correct, but "RSTSRC |= 0x02" is incorrect.
6. Make certain that all writes to the RSTSRC register explicitly set the PORSF bit to a 1. Areas to check are initialization code which enables other reset sources, such as the Missing Clock Detector or Comparator, for example, and instructions which force a Software Reset. A global search on "RSTSRC" can quickly verify this.

19.4.2. PSWE Maintenance

1. Reduce the number of places in code where the PSWE bit (b0 in PSCTL) is set to a 1. There should be exactly one routine in code that sets PSWE to a 1 to write Flash bytes and one routine in code that sets both PSWE and PSEE both to a 1 to erase Flash pages.
2. Minimize the number of variable accesses while PSWE is set to a 1. Handle pointer address updates and loop maintenance outside the "PSWE = 1;... PSWE = 0;" area. Code examples showing this can be found in “AN201: Writing to Flash from Firmware," available from the Silicon Laboratories website.
3. Disable interrupts prior to setting PSWE to a 1 and leave them disabled until after PSWE has been reset to 0. Any interrupts posted during the Flash write or erase operation will be serviced in priority order after the Flash operation has been completed and interrupts have been re-enabled by software.
4. Make certain that the Flash write and erase pointer variables are not located in XRAM. See your compiler documentation for instructions regarding how to explicitly locate variables in different memory areas.
5. Add address bounds checking to the routines that write or erase Flash memory to ensure that a routine called with an illegal address does not result in modification of the Flash.

Port	P0								P1								P2
Pin Number	0	1	2	3	4	5	6	7	0	1	2	3	4[1]	5[1]	6[1]	7[1]	0
Special Function Signals	VREF	AGND	XTAL1	XTAL2			CNVSTR										Signal Unavailable to Crossbar
TX0					■												
RX0						■											
SCK	■																
MISO		■															
MOSI			■														
NSS[2]				■													
SDA																	
SCL																	
CP0																	
CP0A																	
SYSCLK																	
CEX0							■										
CEX1								■									
CEX2									■								
ECI																	
T0																	
T1																	
Pin Skip Settings	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
	P0SKIP								P1SKIP								

In this example, the crossbar is configured to assign the UART TX0 and RX0 signals, the SPI signals, and the PCA signals. Note that the SPI signals are assigned as multiple signals, and there are no pins skipped using the P0SKIP or P1SKIP registers.

■ These boxes represent the port pins which are used by the peripherals in this configuration.

1st TX0 is assigned to P0.4
2nd RX0 is assigned to P0.5
3rd SCK, MISO, MOSI, and NSS are assigned to P0.0, P0.1, P0.2, and P0.3, respectively.
4th CEX0, CEX1, and CEX2 are assigned to P0.6, P0.7, and P1.0, respectively.

All unassigned pins can be used as GPIO or for other non-crossbar functions.

Notes:
1. P1.4-P1.7 are not available on 16-pin packages.
2. NSS is only pinned out when the SPI is in 4-wire mode.

Figure 23.5. Priority Crossbar Decoder Example 1—No Skipped Pins

SFR Definition 23.1. XBR0: Port I/O Crossbar Register 0

Bit	7	6	5	4	3	2	1	0
Name			CP0AE	CP0E	SYSCKE	SMB0E	SPI0E	URT0E
Type	R	R	R/W	R/W	R/W	R/W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

SFR Address = 0xE1

Bit	Name	Function
7:6	Unused	Read = 00b. Write = don't care.
5	CP0AE	**Comparator0 Asynchronous Output Enable.** 0: Asynchronous CP0 unavailable at Port pin. 1: Asynchronous CP0 routed to Port pin.
4	CP0E	**Comparator0 Output Enable.** 0: CP0 unavailable at Port pin. 1: CP0 routed to Port pin.
3	SYSCKE	**SYSCLK Output Enable.** 0: $\overline{\text{SYSCLK}}$ unavailable at Port pin. 1: $\overline{\text{SYSCLK}}$ output routed to Port pin.
2	SMB0E	**SMBus I/O Enable.** 0: SMBus I/O unavailable at Port pins. 1: SMBus I/O routed to Port pins.
1	SPI0E	**SPI I/O Enable.** 0: SPI I/O unavailable at Port pins. 1: SPI I/O routed to Port pins. Note that the SPI can be assigned either 3 or 4 GPIO pins.
0	URT0E	**UART I/O Output Enable.** 0: UART I/O unavailable at Port pin. 1: UART TX0, RX0 routed to Port pins P0.4 and P0.5.

SFR Definition 23.2. XBR1: Port I/O Crossbar Register 1

Bit	7	6	5	4	3	2	1	0
Name	WEAKPUD	XBARE	T1E	T0E	ECIE		PCA0ME[1:0]	
Type	R/W	R/W	R/W	R/W	R/W	R	R/W	R/W
Reset	0	0	0	0	0	0	0	0

SFR Address = 0xE2

Bit	Name	Function
7	WEAKPUD	**Port I/O Weak Pullup Disable.** 0: Weak Pullups enabled (except for Ports whose I/O are configured for analog mode). 1: Weak Pullups disabled.
6	XBARE	**Crossbar Enable.** 0: Crossbar disabled. 1: Crossbar enabled.
5	T1E	**T1 Enable.** 0: T1 unavailable at Port pin. 1: T1 routed to Port pin.
4	T0E	**T0 Enable.** 0: T0 unavailable at Port pin. 1: T0 routed to Port pin.
3	ECIE	**PCA0 External Counter Input Enable.** 0: ECI unavailable at Port pin. 1: ECI routed to Port pin.
2	Unused	Read = 0b; Write = Don't Care.
1:0	PCA0ME[1:0]	**PCA Module I/O Enable Bits.** 00: All PCA I/O unavailable at Port pins. 01: CEX0 routed to Port pin. 10: CEX0, CEX1 routed to Port pins. 11: CEX0, CEX1, CEX2 routed to Port pins.

SFR Definition 23.8. P0MDIN: Port 0 Input Mode

Bit	7	6	5	4	3	2	1	0
Name	P0MDIN[7:0]							
Type	R/W							
Reset	1	1	1	1	1	1	1	1

SFR Address = 0xF1

Bit	Name	Function
7:0	P0MDIN[7:0]	**Analog Configuration Bits for P0.7–P0.0 (respectively).** Port pins configured for analog mode have their weak pullup, digital driver, and digital receiver disabled. **In order for the P0.n pin to be in analog mode, there MUST be a '1' in the Port Latch register corresponding to that pin.** 0: Corresponding P0.n pin is configured for analog mode. 1: Corresponding P0.n pin is not configured for analog mode.

SFR Definition 23.9. P0MDOUT: Port 0 Output Mode

Bit	7	6	5	4	3	2	1	0
Name	P0MDOUT[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

SFR Address = 0xA4

Bit	Name	Function
7:0	P0MDOUT[7:0]	**Output Configuration Bits for P0.7–P0.0 (respectively).** These bits are ignored if the corresponding bit in register P0MDIN is logic 0. 0: Corresponding P0.n Output is open-drain. 1: Corresponding P0.n Output is push-pull.

SFR Definition 28.8. TMR2CN: Timer 2 Control

Bit	7	6	5	4	3	2	1	0
Name	TF2H	TF2L	TF2LEN	TF2CEN	T2SPLIT	TR2		T2XCLK
Type	R/W	R/W	R/W	R/W	R/W	R/W	R	R/W
Reset	0	0	0	0	0	0	0	0

SFR Address = 0xC8; Bit-Addressable

Bit	Name	Function
7	TF2H	**Timer 2 High Byte Overflow Flag.** Set by hardware when the Timer 2 high byte overflows from 0xFF to 0x00. In 16 bit mode, this will occur when Timer 2 overflows from 0xFFFF to 0x0000. When the Timer 2 interrupt is enabled, setting this bit causes the CPU to vector to the Timer 2 interrupt service routine. This bit is not automatically cleared by hardware.
6	TF2L	**Timer 2 Low Byte Overflow Flag.** Set by hardware when the Timer 2 low byte overflows from 0xFF to 0x00. TF2L will be set when the low byte overflows regardless of the Timer 2 mode. This bit is not automatically cleared by hardware.
5	TF2LEN	**Timer 2 Low Byte Interrupt Enable.** When set to 1, this bit enables Timer 2 Low Byte interrupts. If Timer 2 interrupts are also enabled, an interrupt will be generated when the low byte of Timer 2 overflows.
4	TF2CEN	**Timer 2 Comparator Capture Enable.** When set to 1, this bit enables Timer 2 Comparator Capture Mode. If TF2CEN is set, on a rising edge of the Comparator0 output the current 16-bit timer value in TMR2H:TMR2L will be copied to TMR2RLH:TMR2RLL. If Timer 2 interrupts are also enabled, an interrupt will be generated on this event.
3	T2SPLIT	**Timer 2 Split Mode Enable.** When this bit is set, Timer 2 operates as two 8-bit timers with auto-reload. 0: Timer 2 operates in 16-bit auto-reload mode. 1: Timer 2 operates as two 8-bit auto-reload timers.
2	TR2	**Timer 2 Run Control.** Timer 2 is enabled by setting this bit to 1. In 8-bit mode, this bit enables/disables TMR2H only; TMR2L is always enabled in split mode.
1	Unused	Read = 0b; Write = Don't Care.
0	T2XCLK	**Timer 2 External Clock Select.** This bit selects the external clock source for Timer 2. If Timer 2 is in 8-bit mode, this bit selects the external oscillator clock source for both timer bytes. However, the Timer 2 Clock Select bits (T2MH and T2ML in register CKCON) may still be used to select between the external clock and the system clock for either timer. 0: System clock divided by 12. 1: External clock divided by 8 (synchronized with SYSCLK when not in suspend).